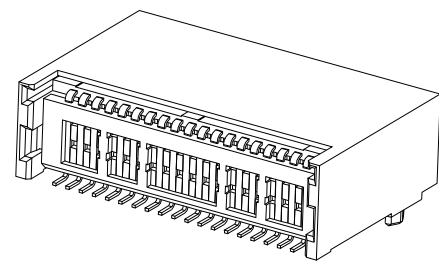
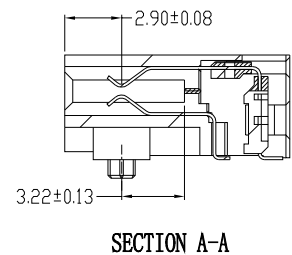
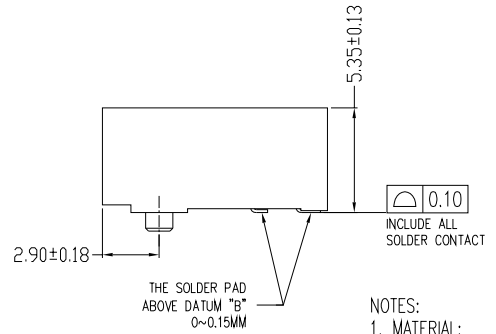
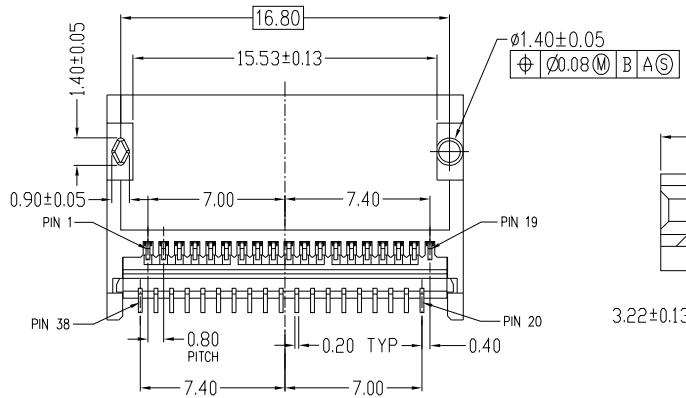
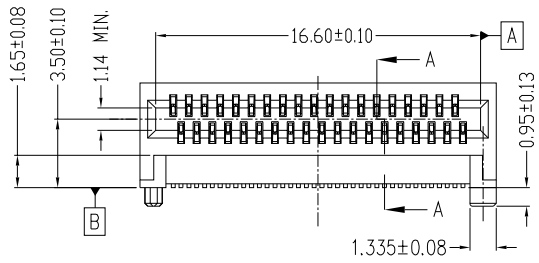
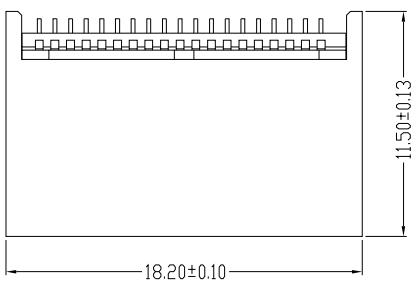


Product Number	Contact Area Plated
10132344-101LF	0.38um Au
10132344-102LF	0.76um Au



- NOTES:
- MATERIAL:  
HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0, BLACK  
TERMINAL : NICKEL COPPER ALLOY
  - PLATING SPEC AS BELOW:  
OPTION 1  
CONTACT AREA PLATE NICKEL 2.54um MIN, PLATE Gold 0.38um MIN  
SOLDER AREA PLATE NICKEL 2.54um MIN, PLATE MATTE TIN 2.54~5.09um  
OPTION 2  
CONTACT AREA PLATE NICKEL 2.54um MIN, PLATE Gold 0.76um MIN  
SOLDER AREA PLATE NICKEL 2.54um MIN, PLATE MATTE TIN 2.54~5.09um
  - ELECTRICAL CHARACTERISTICS  
CONTACT CURRENT RATING: 0.5 AMPERE  
VOLTAGE RATING: 30VAC  
CONTACT RESISTANCE: 40 MILLOHMS MAX  
DIELECTRIC WITHSTANDING VOLTAGE: 300VDC
  - ENVIRONMENT  
OPERATION TEMPERATURE: -40°C TO 85°C
  - PRODUCT SPECIFICATION: GS-12-622
  - PACKAGE PER GS-14-920 AND GS-14-1400
  - APPLICATION SPECIFICATION: GS-20-126

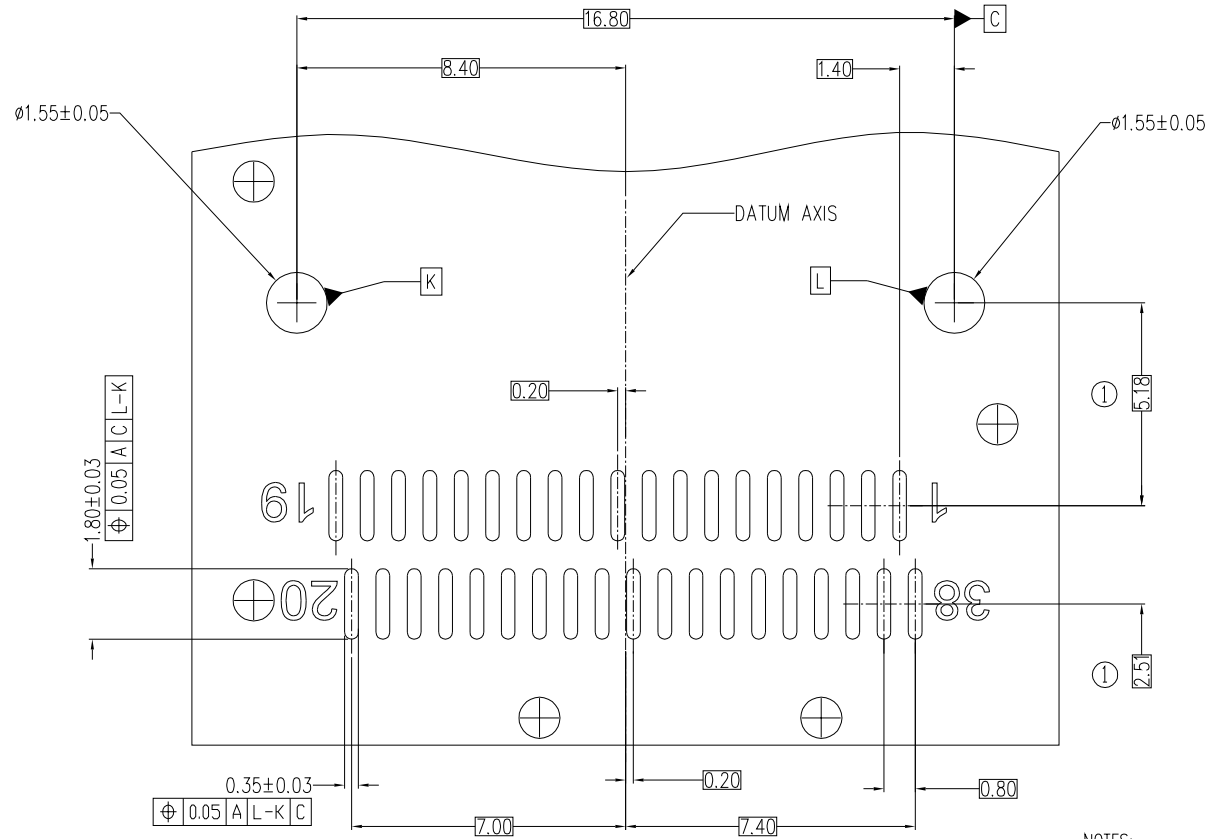


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spec ref	RELEASE	dr	Art Lin	2014-12-15	projection	size	scale			
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Art Lin	2014-12-15		A4	1:1			
ISO406		chr	-	-		ecn no				
ISO1101		appr	Collins Lu	2014-12-16	product family	QSFP+	rel level	Released		
surface	linear	0.X	±0.15		title	10132344	rev			
ISO1302		0.XX	±0.05					cat. no.	-	Product-Customer Drw
	0.XXX	±	Product-Customer Drw							
angular	0°	±0.5°	www.fci.com	www.fci.com	cat. no.	-	Product-Customer Drw	sheet 1 of 3		

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# MOTHERBOARD FOOTPRINT RECOMMENDATION



Scale 2:1

NOTES:  
 1. DIMENSION TO CENTERLINE OF PAD  
 2. DATUM A IS THE TOP SURFACE OF THE HOST BOARD

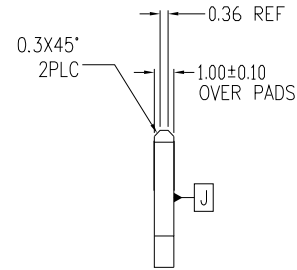
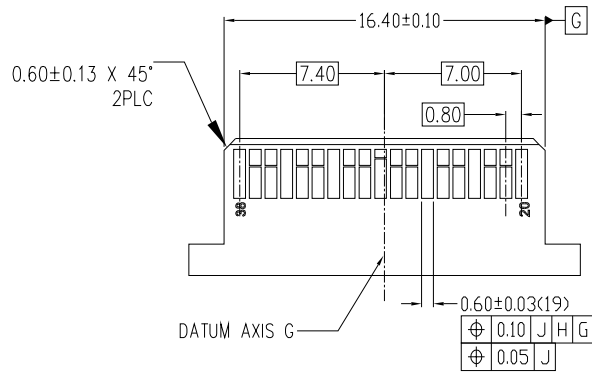


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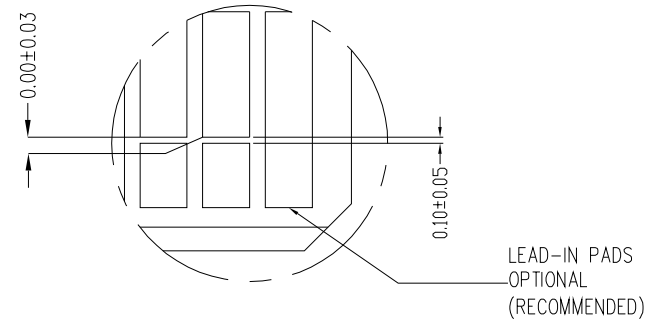
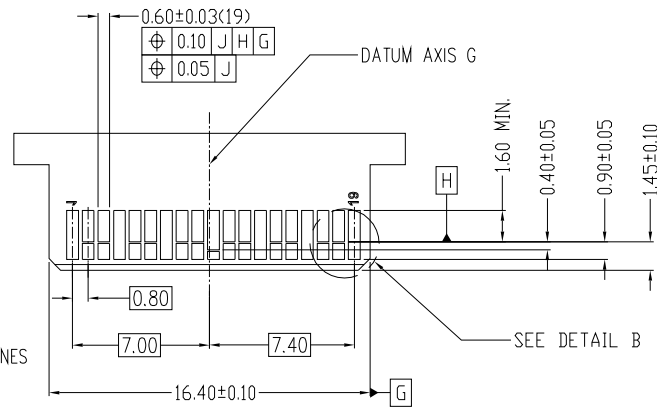
spec ref	RELEASE			dr	Art Lin	2014-12-15	projection	MM	size	A4	scale	1:1
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng	Art Lin	2014-12-15			ecn no			
ISO406				chr	-	-	← →					
ISO1101				appr	Collins Lu	2014-12-16	product family	QSFPP+	rel level	Released		
surface	linear	0.X	±0.15		title	QSFPP+ Connector		dwg no	10132344		rev	A
ISO1302		0.XX	±0.05			38 Pins SMT Type						
	0.XXX	±	www.fci.com			cat. no.	-					
angular		0°	±0.5°									

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# MODULE BOARD FOOTPRINT RECOMMENDATION



- NOTES:
- CONTACT PAD PLATING:  
0.38 MICROMETERS MIN GOLD OVER  
1.27 MICROMETERS MIN NICKEL
  - NO SOLDER MASK WITHIN 0.05MM OF  
DEFINED PAD LOCATIONS
  - ALTERNATE CONTACT PAD PLATING  
0.03 MICROMETERS MIN GOLD OVER  
0.30 MICROMETERS MIN PALLADIUM OVER  
1.27 MICROMETERS MIN NICKEL



**DETAIL B**  
Scale 4:1

DATUM H TARGETS ARE DEFINED BY THE RESPECTIVE PAD CENTERLINES AND THE LEADING EDGE OF THE TARGET PADS

spec ref	RELEASE	dr	Art Lin	2014-12-15	projection	size	scale		
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Art Lin	2014-12-15		A4	1:1		
ISO406		chr	-	-		ecn no			
ISO1101		appr	Collins Lu	2014-12-16	product family	QSFP+	rel level	Released	
surface	<input checked="" type="checkbox"/> linear  <input type="checkbox"/> angular		title QSFP+ Connector 38 Pins SMT Type	www.fci.com	cat. no.	dwg no 10132344	rev A		
ISO1302								<table border="1"> <tr> <td>0.X</td> <td>±0.15</td> </tr> <tr> <td>0.XX</td> <td>±0.05</td> </tr> <tr> <td>0.XXX</td> <td>±</td> </tr> <tr> <td>0°</td> <td>±0.5°</td> </tr> </table>	0.X
0.X	±0.15								
0.XX	±0.05								
0.XXX	±								
0°	±0.5°								
Pro/E File - REV C - 2009-06-09		Product-Customer Drw		sheet 3 of 3					



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